



**RoHS
Compliant**

Full Flange Attenuators 100 Watts

General Specifications

Resistive Element	Thick film
Substrate	ALN ceramic
Cover	Alumina Ceramic
Mounting Flange	Copper, Nickel plated per QQ-N-290
Lead(s):	99.99% pure silver (.006" thick)

Features:

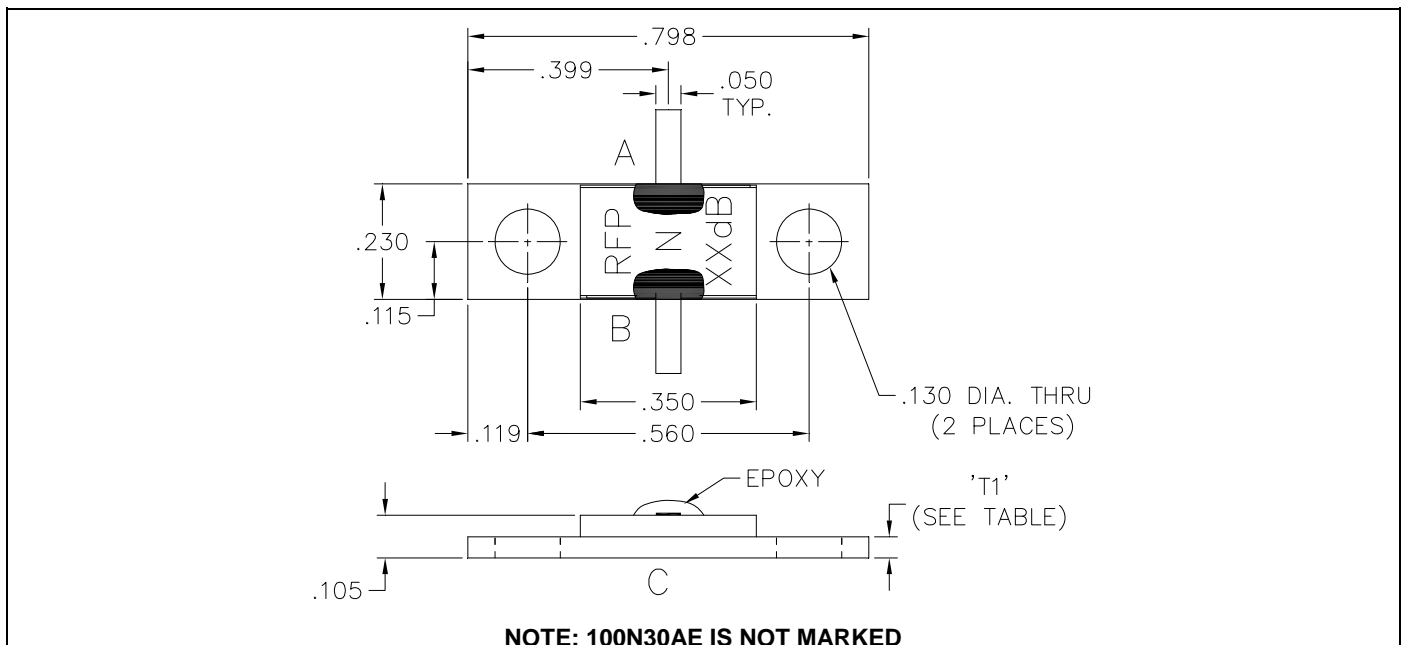
- DC – See table
- 100 Watts
- ALN Ceramic
- Welded Silver Leads
- Non-Nichrome Resistive Element
- Low VSWR
- 100% Tested

Electrical Specifications

Attenuation Range:	1, 2, 3, 4, 5, 6, 9, 10, 20, 30 db
Frequency Range:	DC – See Chart
Power:	100 Watts
V.S.W.R.:	1.25 :1

Notes: Tolerance is $\pm 0.010"$, unless otherwise specified. Designed to meet or exceed applicable portions of MIL-E-5400. All dimensions in inches. Lead length 0.150" minimum.
Specifications subject to change without notice.

Outline Drawing



100NXXAE (097) Rev E

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Specifications

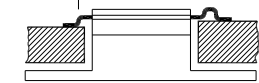
RESISTOR VALUE CHART

ATTENUATION	VALUE (A-B)	VALUE (A-C)	VALUE (B-C)	TOL.	FREQUENCY	R.F.P. STOCK P/N	'T1'
1dB+0.25/- .6dB	4.8Ω	435 Ω	435 Ω	±4%	DC-2.2GHz.	RFP-100N1AE	.042
1.5dB±0.30dB	7.4Ω	294 Ω	294 Ω	±4%	DC-2.2GHz.	RFP-100N1R5AE	.042
2dB±0.40dB	9.6Ω	232 Ω	232 Ω	±4%	DC-2.2GHz.	RFP-100N2AE	.042
3dB±0.40dB	15.2Ω	155 Ω	155 Ω	±4%	DC-2.5GHz.	RFP-100N3AE	.042
4dB±0.40dB	22Ω	131Ω	131Ω	±4%	DC-2.5GHz.	RFP-100N4AE	.042
5dB±0.40dB	28.5Ω	94.7Ω	94.7Ω	±4%	DC-3.0GHz.	RFP-100N5AE	.042
6dB±0.40dB	33.7Ω	82.5 Ω	82.5 Ω	±4%	DC-3.0GHz.	RFP-100N6AE	.042
9dB±1.0dB	50.6Ω	61.3Ω	61.3Ω	±4%	DC-2.2GHz.	RFP-100N9AE	.042
10dB+1.0/-1.75dB	56.0Ω	60 Ω	60Ω	±4%	DC-2.2GHz.	RFP-100N10AE	.042
20dB±0.50dB	81.7Ω	50.9 Ω	50.9 Ω	±4%	DC-2.0GHz.	RFP-100N20AE	.062
30dB±1.00dB	94Ω	50.1Ω	50.1Ω	±4%	DC-2.5GHz.	RFP-100N30AE	.062

Suggested Mounting Procedure:

Power Derating:

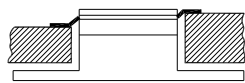
.025 MIN.
(2 PLACES)



BOARD LOWER
THAN LEAD.

BOARD EVEN
WITH LEAD.

SUGGESTED STRESS RELIEF METHODS
SCALE: NONE



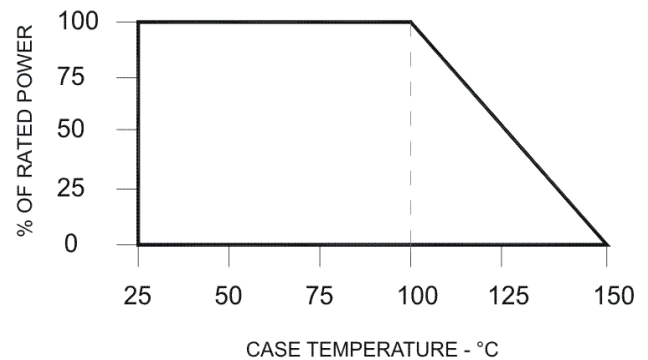
BOARD LOWER
THAN LEAD.

BOARD HIGHER
THAN LEAD.

NOT RECOMMENDED APPLICATION
SCALE: NONE

SUGGESTED MOUNTING PROCEDURES:

1. MAKE SURE THAT THE DEVICES ARE MOUNTED ON FLAT SURFACES (.001" UNDER THE DEVICE) TO OPTIMIZE THE HEAT TRANSFER.
2. POSITION DEVICE ON MOUNTING SURFACE AND SOLDER IN PLACE USING APPROPRIATE TYPE SOLDER.
3. SOLDER LEADS IN PLACE USING APPROPRIATE TYPE SOLDER WITH A CONTROLLED TEMPERATURE IRON.



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